

Thermal paste GD-3, 30g, 7.5 W/m K

Reference: AM6318

EAN13: -

HS code: 38249996

Product attributes:

Product features:

Color: Gray

Max. operating temperature: 120 °C

Thermal conductivity: 7.5 W/mK



Product description:

Thermal paste GD-3 is designed to improve heat transfer between electronic components and heat sinks. It is used during assembly or maintenance of processors, GPUs, LED elements and other components where it is necessary to fill microscopic irregularities between contact surfaces and promote effective heat dissipation. The packaging in a syringe allows for more precise dosing during application.

Technical specifications

- Product type: thermal paste
- Designation: GD-3
- Thermal conductivity: 7.5 W/m K
- Color: gray
- Density: 2.5 g/cc
- Net weight: 30g
- Operating temperature: -35 to +120 °C
- Packaging: syringe

Functions and features

- It serves to create a thermally conductive interface between the component and the heat sink.
- Helps reduce air gaps between mating surfaces.
- The syringe packaging makes it easy to apply the required amount of material.
- Suitable for use in electronics and thermal management of components.

Ideal for

- Processors and graphics chips
- LED modules and LED lighting with heat sink
- Service and maintenance of cooled electronic devices
- Mounting components on aluminum radiators

Package contents

- 1x GD-3 thermal paste in a syringe, 30 g

Why choose this product?

- Stated thermal conductivity of 7.5 W/m·K for use in the thermal interface of electronic components.
- The syringe design supports cleaner and more precise application.
- The weight of 30 g is suitable for repeated use during assembly and service.
- Designed for applications where there is a need to improve heat transfer between the component and the heat sink.

Installation and operating instructions

- Clean and degrease both contact surfaces before application.
- Apply only a thin, continuous layer in the necessary quantity.
- After application, ensure proper mechanical pressure of the heat sink to the component.
- Avoid contaminating the paste with dust and dirt.

Safety notice

- Use the product only for its intended purpose in the area of thermal bonding of components and heat sinks.
 - When applying to electronic devices, work only on the device that is turned off and unplugged.
 - Avoid contact with eyes, skin, and inside connectors or contacts.
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- Keep out of reach of children.